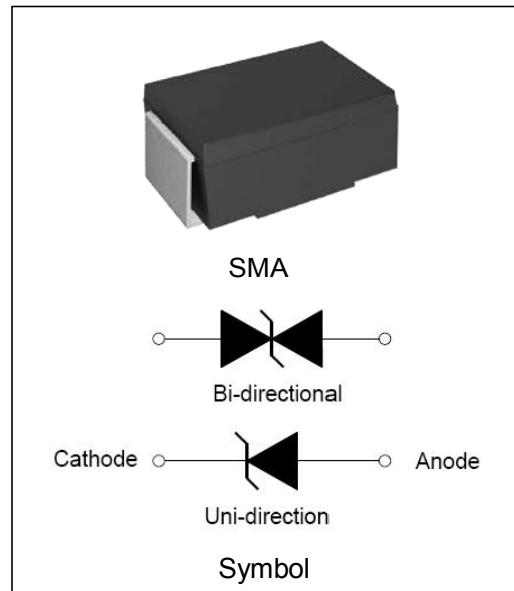


»Features

- Peak power dissipation 400W @10 x 1000 us Pulse
- Low profile package.
- Excellent clamping capability.
- Glass passivated junction.
- Fast response time: typically less than 1ps from 0 Volts to BV min
- IEC 61000-4-2 ESD 30KV(Air), 30KV(Contact)
- ESD protection of data lines in accordance with IEC 61000-4-2
- EFT protection of data lines in accordance with IEC 61000-4-4
- Halogen free and RoHS compliant
- Lead-free finish



»Mechanical Characteristics

- CASE: SMAJ (DO-214AC) Molded Plastic over glass passivated junction.
- Mounting Position: Any
- Polarity: by cathode band denotes uni-directional device, none cathode band denotes bi-directional device.
- Terminal: Solder plated

»Maximum Ratings And Characteristics @ 25°C Ambient Temperature

Parameter	Symbol	Value	Units
Peak Pulse Power Dissipation on 10/1000 us Waveform (Note 1, 2, FIG.1)	P _{PPM}	Min 400	W
Power Dissipation on Infinite Heat Sink at T _L =50°C	P _D	3.3	W
Peak Pulse Current of on 10/1000us Waveform (Note 1, FIG.3)	I _{PPM}	See Table 1	A
Peak Forward Surge Current, 8.3ms Single Half Sine-Wave (Note 2. 3)	I _{FSM}	60	A
Operating Junction Temperature Range	T _J	-55 to 150	°C
Storage Temperature Range	T _{STG}	-55 to 150	°C

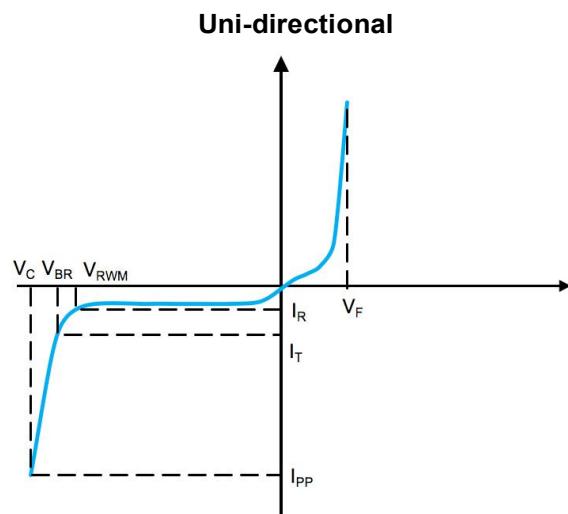
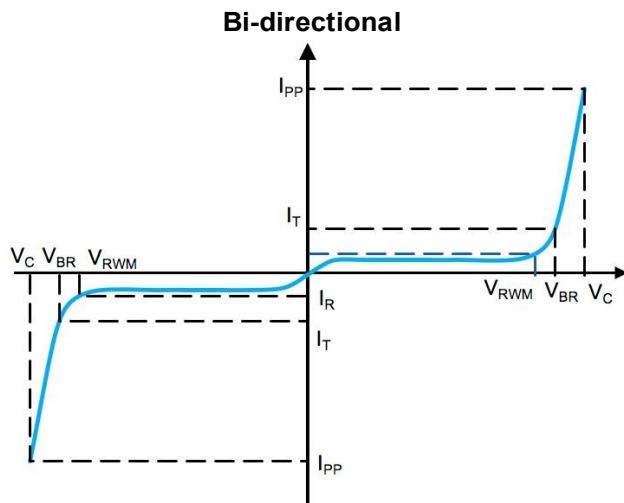
Notes:

1. Non-repetitive current pulse, per Fig.3 and derated above T_A=25°C per Fig.2.
2. Mounted on 5.0x5.0mm² (0.03mm thick) Copper Pads to each terminal.
3. Measured on 8.3ms single half sine-wave, or equivalent square wave, for Unidirectional device only.

»Electrical Specification @ Tamb 25°C

Type Number	Marking		Reverse Stand-Off Voltage	Breakdown Voltage Min. @I _T	Breakdown Voltage Max. @ I _T	Test Current	Maximum Clamping Voltage @I _{PP}	Peak Pulse Current	Reverse Leakage @V _{RMW}	
(Uni)	(Bi)	(Uni)	(Bi)	V _{RMW} (V)	V _{BR MIN} (V)	V _{BR MAX} (V)	I _T (mA)	V _c (V)	I _{PP} (A)	I _R (uA)
SMAJ6.8A	SMAJ6.8CA	SMAJ 6.8A	SMAJ 6.8CA	5.8	6.45	7.14	10	10.5	39.5	500

»I-V Curve Characteristics



P_{PPM} Peak Pulse Power Dissipation - Max power dissipation

V_{RWM} Reverse Stand-off Voltage - Maximum voltage that can be applied to TVS without operation

V_{BR} Breakdown Voltage – Maximum voltage that flows through the TVS at a specified current (I_T)

V_C Clamping Voltage – Peak voltage measured across the TVS at a specified I_{PPM} (peak impulse current)

I_R Reverse Leakage Current – Current measured at V_R

V_F Forward Voltage Drop for Uni-directional

»Ratings and Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

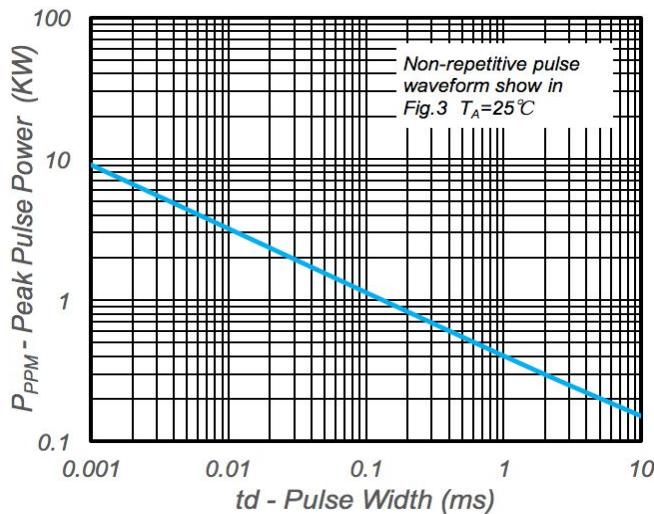


Fig.1 Peak Pulse Power Rating

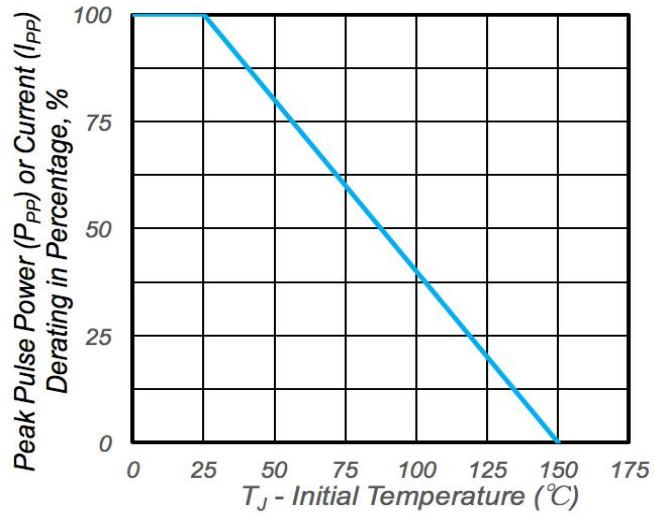


Fig.2 Pulse Derating Cure

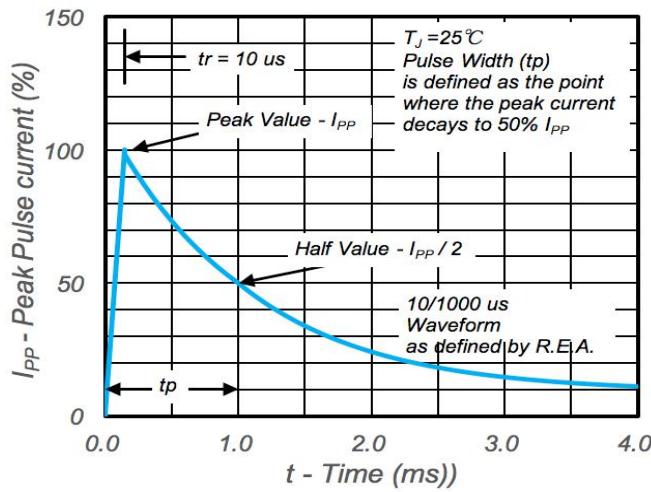


Fig.3 Pulse Waveform

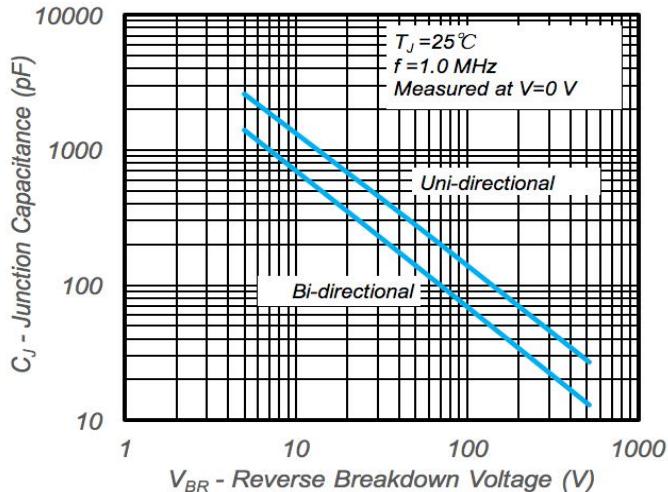
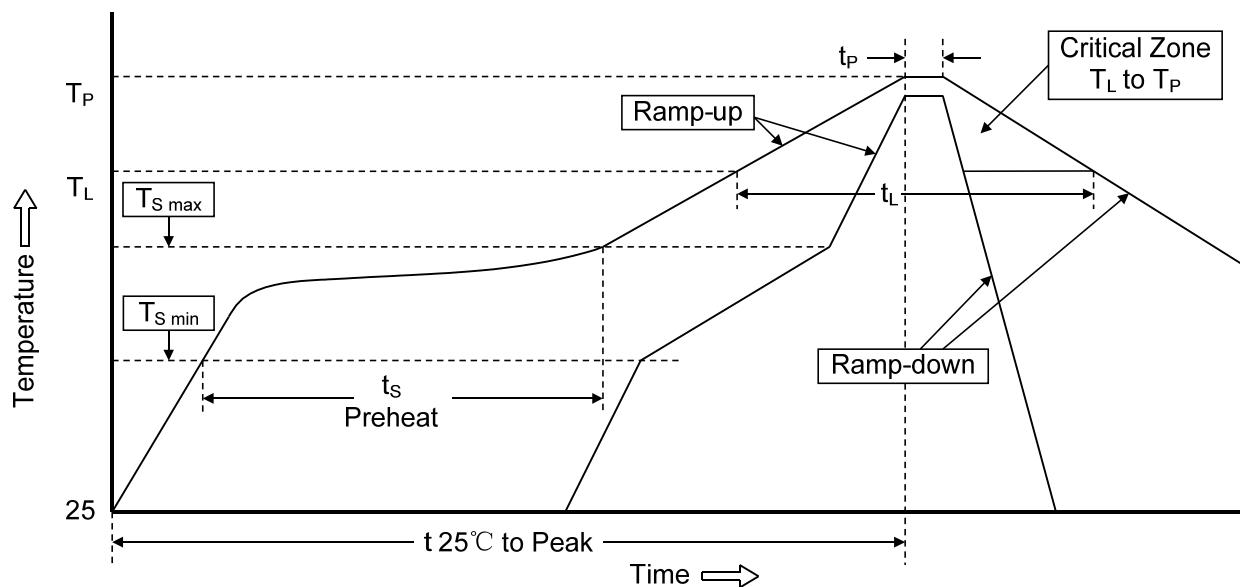


Fig.4 Typical Junction Capacitance

»Recommended Soldering Conditions

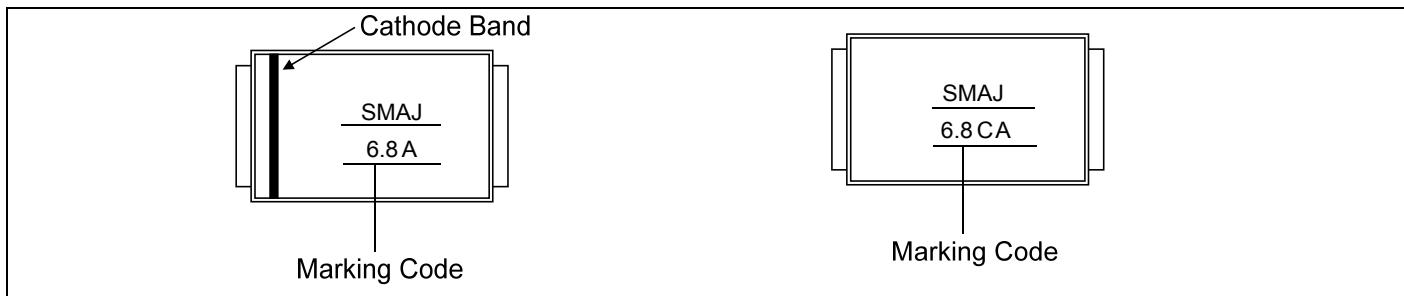
Reflow Soldering



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T _L to T _P)	3°C/second max.
Preheat	
-Temperature Min (T _{S min})	150°C
-Temperature Max (T _{S max})	200°C
-Time (min to max) (t _S)	60-180 seconds
T _{S max} to T _L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T _L)	217°C
-Time (t _L)	60-150 seconds
Peak Temperature (T _P)	260°C
Time within 5°C of actual Peak Temperature (t _P)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

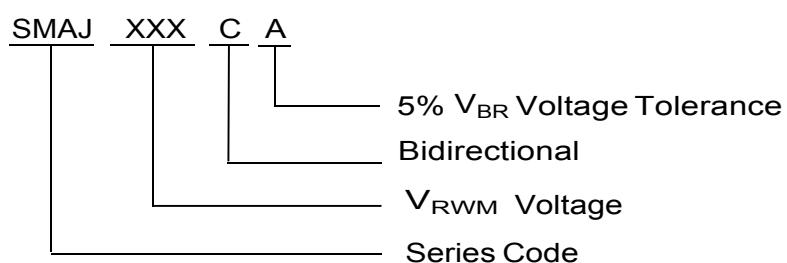
»Marking Code



»Package Outline Dimensions and Pad Layouts (DO-214AC)

Dim	Millimeters		Inches	
	Min	Max	Min	Max
L	4.06	4.57	0.160	0.180
D	2.40	2.84	0.095	0.112
D1	1.30	1.60	0.052	0.063
T	5.01	5.39	0.197	0.213
T1	0.76	1.52	0.030	0.060
d	-	0.203	-	0.008
H	2.15	2.65	0.085	0.104
H1	2.03	2.47	0.080	0.097

»Ordering Information



»Packaging

Symbol	Dimension(mm)
W	12.00±0.20
P0	4.00±0.10
P1	4.00±0.10
P2	2.00±0.10
D0	$\Phi 1.5\pm 0.10$
D1	$\Phi 1.5\pm 0.10$
E	1.75±0.10
F	5.50±0.05
A0	2.79±0.10
B0	5.33±0.10
K0	2.55±0.15
T	0.25±0.05
D2	$\Phi 178.0\pm 2.0$
D3	$\Phi 50.0\text{Min.}$
D4	$\Phi 13.0\pm 0.5$
W1	16.0±2.0
Quantity:2000PCS	
D5	$\Phi 330.0\pm 2.0$
D6	$\Phi 13.5\pm 0.5$
H	2.5±1.0
W2	16.0±2.0
Quantity: 5000PCS	